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HARMONIZED SYSTEM
REVIEW SUB-COMMITTEE
-
28th Session
-

NR0461E1
(Annex I and II)

O. Eng.

Brussels, 1 August 2003.

POSSIBLE AMENDMENT OF NOTE 5 TO CHAPTER 84

POSSIBLE AMENDMENT OF NOTE 5 TO CHAPTER 85

(SECRETARIAT PROPOSALS)

(Items III.A.23 and III.A.24 on Agenda)

Reference documents :

Note 5 to Chapter 84 :

NR0115E1 (RSC/22)
NR0133E2, Annex D/5(RSC/22 – Report)
NR0188E1 (RSC/24)
NR0201E1 (RSC/24)
NR0205E2, Annex E (RSC/24 – Report)
NR0323E1 (RSC/26)
NR0332E3, Annex D/5 (RSC/26 – Report)
NR0334E1 (RSC/WG/1)
NR0335E1 (RSC/WG/1)
NR0387E1 (RSC/WG/1)
NR0400E3, Annex G (RSC/27 – Report)
NR0421E1 (RSC/28)

Note 5 to Chapter 85 :

NR0323E1 (RSC/26)
NR0326E1 (RSC/26)
NRO387 (RSC/WG/1
Informal Group
NR0332E3, Annexes D/8 and F/21 (RSC/26 – Report)
NR0334E1 (RSC/WG/1
Summary Report (RSC/WG/1)
NR0422E1 (RSC/28)

I. BACKGROUND

1. Following the preparation of Docs. NR0421E1 and NR0422E1, the Secretariat, on 30 June 2003, received the following notes from the Japanese Administration concerning the possible amendment of Note 5 to Chapter 84 and Note 5 to Chapter 85. The Secretariat has reproduced these notes in the attached Annexes without comment.

Note : Shaded parts will be removed when documents are placed on the WCO documentation database available to the public.

File Nos. 2818 A
2938

II. SECRETARIAT COMMENTS

2. The Secretariat would draw the Sub-Committee's attention to Annex II, paragraph 5, wherein there is a reference to attached figures and diagrams illustrating a few examples of multichip-type integrated circuits. The attached electronic file with this data sent with the Japanese submission was corrupted and, as a result, the Secretariat was not able to reproduce these figures and diagrams in the document. Arrangements have been made to have paper copies available in the meeting room.

II. CONCLUSION

3. The Review Sub-Committee is invited to examine the comments by the Japanese Administration when it examines the relevant Agenda Items.

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NOTE FROM THE JAPANESE ADMINISTRATION

Possible amendment of Note 5 (A)(a) to Chapter 84

1. "The problem with current Note 5(A)(a) to Chapter 84 is the difficulty in determining the scope of the machines subject to this definition. This difficulty in understanding the current definition results in different methods of implementation.

2. Current definition (2) refers to the fact that any external program can run on the machine. However, it is often implemented on the basis of the programmability of the machine by the user, which is solely dependent on the programming language rather than the hardware.

3. Current definition (4) refers to branch conditions in the stored program computer, which is also seldom understood.

4. The Japanese proposal is structured so that the general public can determine whether a machine is within the scope of the definition, regardless of whether a program (e.g., OS) is installed or not.

   Its structure is as follows :

   (1) A central processing unit (CPU) that processes programs;
   (2) A main memory for storing necessary programs and data;
   (3) Means for reading and loading external programs

5. The meaning of points (1) and (2) are clear.

6. In a personal computer, point (3) refers to a program for loading the OS from an external source, called the bootstrap loader, which usually located within a BIOS extension ROM. In a mainframe computer, it refers to a system called the service processor. In general purpose computers (also called the "stored-program computers"), programs are separated from the hardware, and its essential nature is loading and executing programs specified by the user from external sources.

7. Taking the aforementioned into account, the following is the Japanese proposal :

   Chapter 84.

   Page 1392. Note 5 (A) (a).

   Delete and substitute :

   "(a) Digital machines, (1) comprising, at least a central processing unit (CPU) and a main memory designed for storing programs or data necessary for the execution of the programs; (2) being designed for loading and executing any external program;""

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NOTE FROM THE JAPANESE ADMINISTRATION

Possible amendment of Note 5 (B) to Chapter 85

1. "In step with the increasing applications of electronics equipment in recent years, demand has become remarkably stronger for higher functionality, further miniaturisation and less energy consumption. To meet such demands, it has become necessary to put the components used in super high density packaging.

2. In the field of integrated circuits, which are the main components of electronics equipment, integrated circuits of super-high levels of integration have been realised through progress made in nanoscale technologies. Integrated circuits have undergone great progress as a result of progress made in super high density packaging technologies. A wide variety of sophisticated super high density packages (MCMs, MCPs, SIPs, etc.) in manifold combinations of integrated circuits together with each other or with discrete components have been developed and provided for practical use. This has greatly contributed to the evolution of electronics equipment.

3. These super high density packages have made their appearance among commodities of roughly the same shape as semiconductor integrated circuits made up of one chip under the HS classifications. They consist of a combination of integrated circuit chip(s) and discrete component(s) in a form of two or-three dimensional manner. Today, they are treated as integrated circuits in general business transactions.

4. Accordingly, in the HS nomenclature, it is reasonable to define these multichip-type integrated circuits (MCMs, MCPs, SIPs, etc.) as one class of integrated circuits.

5. For your reference, the attached figures and diagrams illustrate a few examples of multichip-type integrated circuits.

6. Taking the aforementioned into account, the following is the Japanese proposal :

Chapter 85.

Page 1617. Note 5 (B) to Chapter 85.

Insert following new item (c) :

"(c) Multichip-type integrated circuits refer to the following articles : Components in which one or more monolithic integrated circuits (unencapsulated) and other passive or active elements (including monolithic integrated circuits) are combined and interconnected on a substrate (made of glass, ceramic, resin, metal, or other material) and encapsulated into a single body. Components in which a number of monolithic integrated circuits (unencapsulated) are stacked with each other may be unencapsulated.""